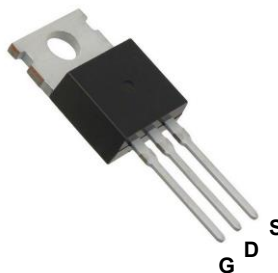
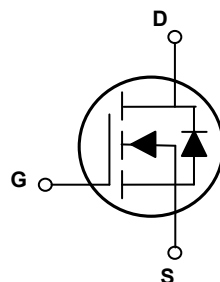


## Main Product Characteristics

$BV_{DSS}$	150V
$R_{DS(ON)}$	5.4mΩ (TYP)
$I_D$	175A



TO-220



Schematic Diagram

## Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



## Description

The GSGH7R515 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

## Absolute Maximum Ratings ( $T_C=25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	$V_{DS}$	150	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous ( $T_C=25^{\circ}\text{C}$ ) <sup>1</sup>	$I_D$	175	A
Drain Current-Continuous ( $T_C=100^{\circ}\text{C}$ )		124	
Drain Current-Pulsed <sup>2</sup>	$I_{DM}$	690	A
Single Pulse Avalanche Energy <sup>3</sup>	$E_{AS}$	803	mJ
Power Dissipation ( $T_A=25^{\circ}\text{C}$ )	$P_D$	376	W
Linear Derating Factor ( $T_A=25^{\circ}\text{C}$ )		2.5	
Junction-to-Case	$R_{\theta JC}$	0.4	$^{\circ}\text{C/W}$
Junction-to-Ambient (PCB Mounted, Steady-State) <sup>4</sup>	$R_{\theta JA}$	62.5	$^{\circ}\text{C/W}$
Operating Junction Temperature Range	$T_J$	-55 To +175	$^{\circ}\text{C}$
Storage Temperature Range	$T_{STG}$	-55 To +175	$^{\circ}\text{C}$

**Electrical Characteristics** ( $T_A=25^{\circ}\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>On / Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	150	-	-	V
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=150V, V_{GS}=0V, T_J=25^{\circ}\text{C}$	-	-	1	$\mu A$
		$V_{DS}=150V, V_{GS}=0V, T_J=125^{\circ}\text{C}$	-	-	50	$\mu A$
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=100A$	-	5.4	7.5	m $\Omega$
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	2.1	3.0	3.9	V
<b>Dynamic and Switching Characteristics</b>						
Total Gate Charge	$Q_g$	$V_{DS}=120V, I_D=100A$ $V_{GS}=10V$	-	81	-	nC
Gate-Source Charge	$Q_{gs}$		-	29	-	
Gate-Drain Charge	$Q_{gd}$		-	15	-	
Turn-On Delay Time	$t_{d(on)}$	$V_{DS}=75V, R_G=2.5\Omega$ $V_{GS}=10V, I_D=80A$	-	16.5	-	nS
Rise Time	$t_r$		-	106.3	-	
Turn-Off Delay Time	$t_{d(off)}$		-	60.6	-	
Fall Time	$t_f$		-	104.6	-	
Input Capacitance	$C_{iss}$	$V_{DS}=25V, V_{GS}=0V,$ $F=1MHz$	-	5400	-	pF
Output Capacitance	$C_{oss}$		-	3300	-	
Reverse Transfer Capacitance	$C_{rss}$		-	80	-	
Gate Resistance	$R_g$	$V_{GS}=0V, V_{DS}=0V,$ $F=1MHz$	-	4.3	-	$\Omega$
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Continuous Source Current (Body Diode)	$I_S$	MOSFET symbol showing the integral reverse p-n junction diode	-	-	175	A
Pulsed Source Current (Body Diode)	$I_{SM}$		-	-	690	A
Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_S=80A$	-	1	1.2	V
Reverse Recovery Time	$t_{rr}$	$I_F=80A, di/dt=100A/\mu s, T_J=25^{\circ}\text{C}$	-	110	-	nS
Reverse Recovery Charge	$Q_{rr}$		-	0.36	-	$\mu C$

Note:

1. Pulse test: pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
2. Repetitive rating: Pulsed width limited by maximum junction temperature.
3.  $V_{DD}=50V, L=0.3mH, R_G=25\Omega$ , starting  $T_J=25^{\circ}\text{C}$ .
4. Device mounted on FR-4 PCB, 1inch x 0.85inch x 0.062inch.

## Typical Electrical and Thermal Characteristic Curves

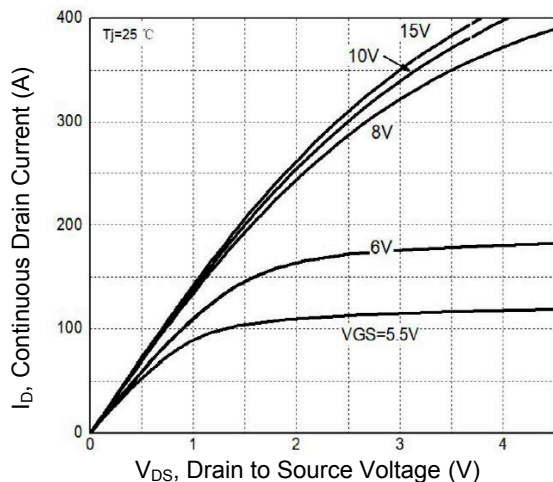


Figure 1. Typical Output Characteristics

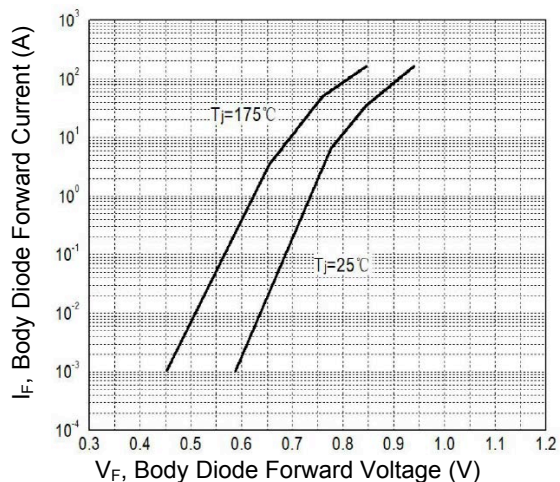


Figure 2. Body Diode Characteristics

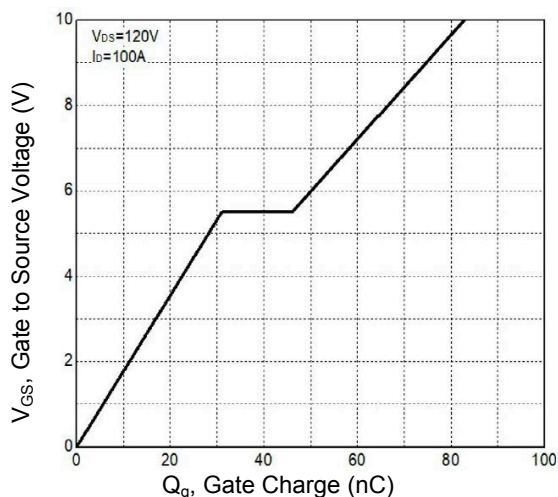


Figure 3. Gate Charge Characteristics

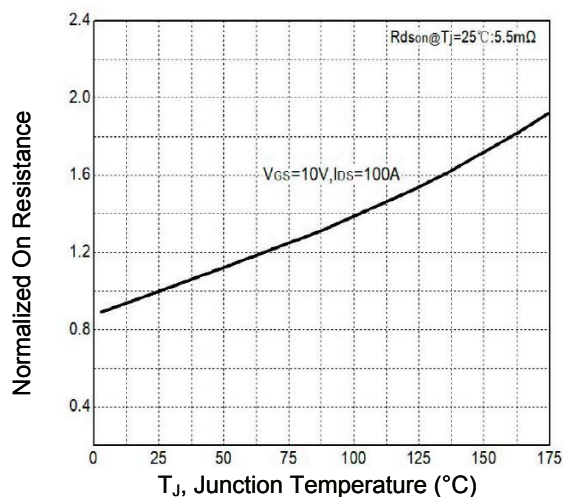


Figure 4. Normalized On-Resistance vs.  $T_J$

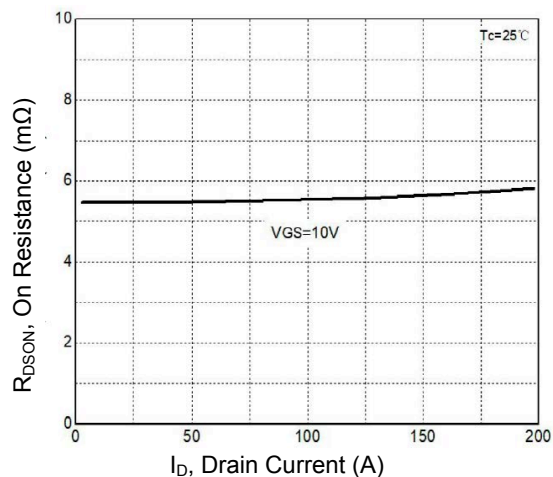


Figure 5. Drain-Source On-Resistance

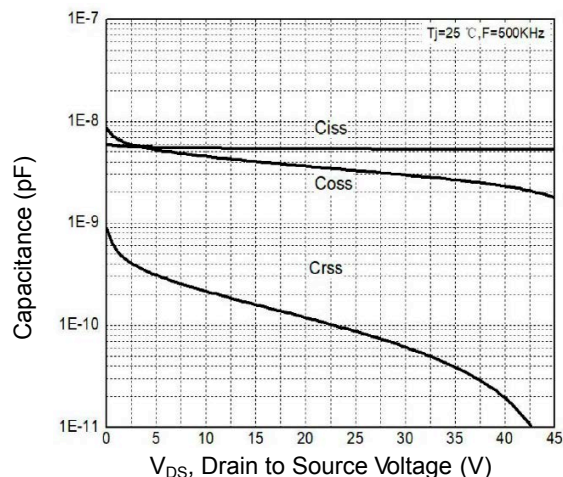
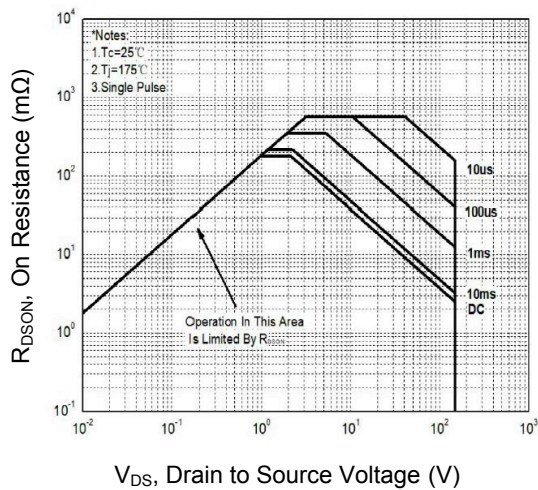
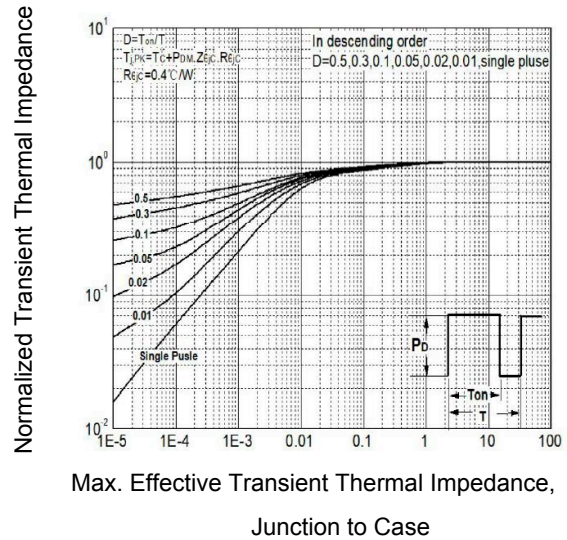


Figure 6. Capacitance Characteristics

## Typical Electrical and Thermal Characteristic Curves

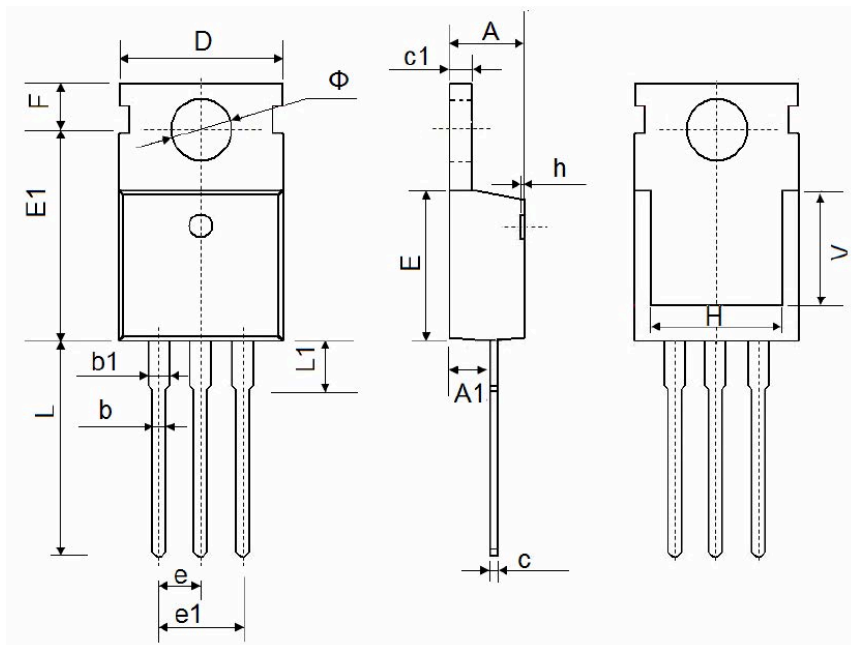


**Figure 7. Maximum Safe Operation Area**



**Figure 8. Thermal Transient Impedance**

## Package Outline Dimensions TO-220



Symbol	Dimesnions in Millimeters		Dimesnions in Inches	
	Min	Max	Min	Max
A	4.400	4.600	0.173	0.181
A1	2.250	2.550	0.089	0.100
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
c	0.330	0.650	0.013	0.026
c1	1.200	1.400	0.047	0.055
D	9.910	10.250	0.390	0.404
E	8.950	9.750	0.352	0.384
E1	12.650	12.950	0.498	0.510
e	2.540 TYP		0.100 TYP	
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
H	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.900	13.400	0.508	0.528
L1	2.850	3.250	0.112	0.128
V	6.900 REF.		0.276 REF.	
Φ	3.400	3.800	0.134	0.150